



WHAT IS CLAIMED IS:

1 1. A method of forming a conductive device, the method

2 comprising:

3 forming a conductive layer on a substrate;

4 etching the conductive layer to form a plurality of conductive traces;

5 etching the conductive layer to form at least one mask feature; and

6 removing substrate material that is not covered by the at least one

7 mask feature so as to form at least one mechanical alignment feature.

1 2. The method of claim 1 wherein the etching steps are
2 performed simultaneously.

3 8. A conductive device produced according to the method of
4 claim 1.

1 9. A method of forming a printed circuit board, the method
2 comprising:

3 forming a conductive layer on a substrate;
4 etching the conductive layer to form multiple conductive traces,
5 each trace having a contact portion,
6 etching the conductive layer to form multiple mask features that
7 cooperate to define a template; and
8 ablating with a laser substrate material that is not covered by the
9 template so as to form a plurality of mechanical alignment features.

1 10. The method of claim 9 wherein the etching steps are
2 performed simultaneously.

Sub A1 > 11. The method of claim 9 wherein the ablating step comprises
2 ablating substrate material so as to form a multiple apertures and multiple side
3 edges, wherein the apertures and the side edges function as mechanical alignment
4 features.

claim 9. > 12. A printed circuit board produced according to the method of